

What is claimed is:

1. A photodetector packaging system, comprising:
an insulating substrate with a shoulder
section; and

5 a wire bond for coupling the photodetector to
the insulating substrate at the shoulder section.

2. The system of Claim 1, further comprising:
optical fiber that directs incident light
directly to the photodetector.

10 3. A method for packaging a photodetector,
comprising:

mounting the photodetector on a insulating
substrate with a shoulder section; and

15 coupling the photodetector to the insulating
substrate shoulder section with a wire bond.

4. The method of Claim 3, wherein the
photodetector is mounted on the insulating substrate
such that the photodetector directly receives incident
light from an optical fiber.

20 5. A system for packaging photodetectors,
comprising:

an insulating substrate with conducting vias;
and

25 a wire bond that couples the photodetector to
the insulating substrate at the conducting vias.

6. The system of Claim 5, further comprising:
conducting tabs coupled to the conducting
vias.

7. The system of Claim 6, wherein the metal tabs
are coupled to a transimpedance amplifier by a wire
bond.

8. The system of Claim 7, wherein the
transimpedance amplifier is coupled to a limiting
amplifier by a wire bond.

9. The system of Claim 8, wherein the limiting
amplifier is coupled to electrical outputs.

10. A method for packaging a photodetector,
comprising:

coupling the photodetector to a insulating
substrate using conducting vias.

11. The method of Claim 10, wherein the
photodetector is coupled to the insulating substrate by
a wire bond.

12. The method of Claim 10, further comprising:
coupling the insulating substrate at the
conducting vias to metal tabs.

13. The method of Claim 12, further comprising:
coupling the metal tab to a transimpedance
amplifier.

14. The method of Claim 13, further comprising:

coupling the transimpedance amplifier to a
limiting amplifier.

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